

Amphenol Taiwan Corporation
Product Change Notification

Part Numbers Concerned :	G88MPXX1XXXEU	Originator:	Karen Su
Product Description:	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)	Issue Date:	2022/07/11
		PCN NO:	PCN_G88MPXX1XXXEU
Distribution:			

Product Change Notice

1. DIM3.06 CHANGE TO DIM3.00 (D4)
2. ADDED WITHOUT BOARDLOCK PCB LAYOUT
3. UPDATE PCB LAYOUT TOLERANCE

Old version part:

Rev.B

New version part:

PCN_ G88MPXX1XXXEU (After release to Rev.C)

Background:

CORRECT MISTAKES ON DRAWINGS AND ORGANIZE PCB LAYOUT DRAWINGS

Product Part Number Affected:

G88MP02102KEU; G88MP04101KEU; G88MP04101MEU; G88MP04102KEU; G88MP04102MEU; G88MP04132KEU; G88MP06102KEU; G88MP06106KEU; G88MP06106MEU; G88MP06122KEU; G88MP06131KEU; G88MP06132KEU; G88MP08101KEU; G88MP08102KEU; G88MP08102MEU; G88MP08132KEU; G88MP08136KEU; G88MP10102KEU; G88MP10112KEU; G88MP12101KEU; G88MP12102KEU; G88MP12106MEU; G88MP14102KEU; G88MP14102MEU; G88MP14122KEU; G88MP16102KEU; G88MP16122KEU; G88MP16122MEU; G88MP18102KEU; G88MP20102KEU; G88MP22101KEU; G88MP22102KEU; G88MP24102KEU; G88MP24102MEU; G88MP24122KEU;

Implementation date:

Immediately effective.

Recommended Action:

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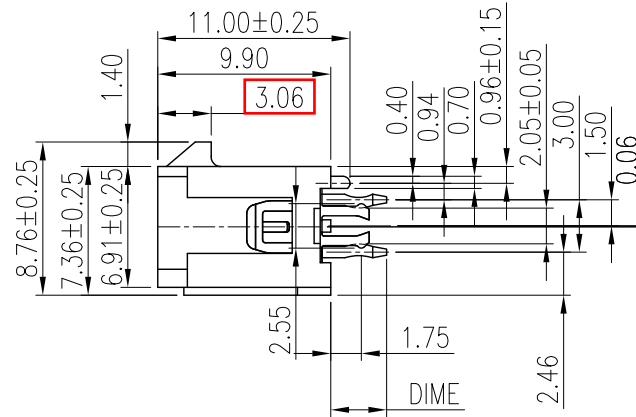
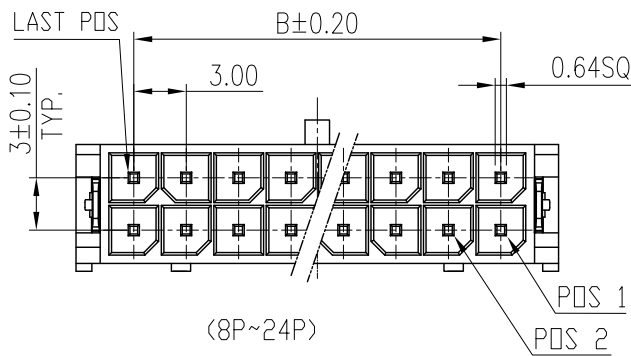
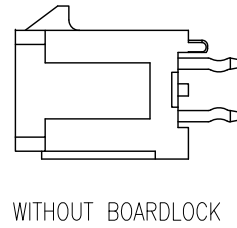
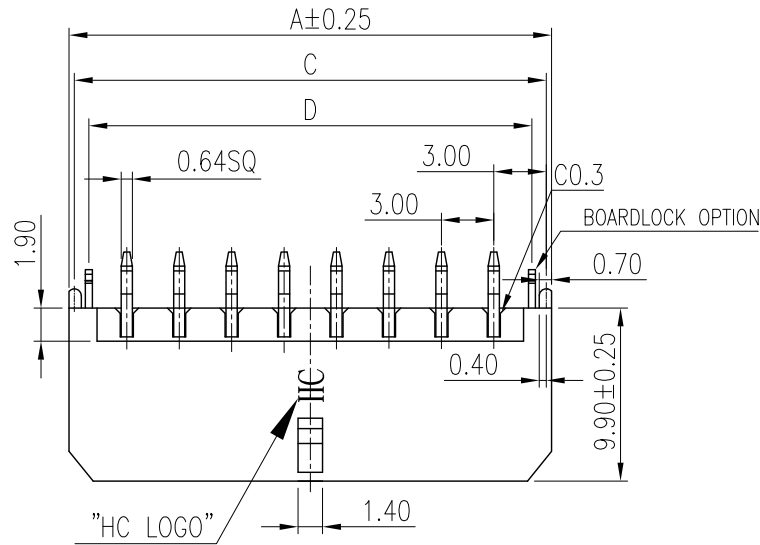
ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAI OPTION	09/13/2016	Roger Tsai

NOTE:

- MATERIAL
INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.
BOARDLOCK: COPPER ALLOY.
- FINISH:
CONTACT: SELECTIVE PLATING. ;
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
BOARDLOCK:
MATTE TIN 100u" MIN. PLATING;
UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- APPLICABLE P.C.BOARD THICKNESS: 1.60mm
- PRODUCT SPECIFICATION REFER TO : PS-7528
- PACKING MUST BE PER AMPHENOL PACKING SPECIFICATION
- TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

PART NO. G88MPXX1XXXEU

No. OF CIRCUIT

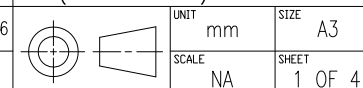
CONTACT FINISH
0: MATTE TIN (OVERALL)
UNDER PLATING NICKEL
50 u" THICKNESS MIN
1: FLASH GOLD (OVERALL)
2: 15 u" GOLD
3: 30 u" GOLD

BOARDLOCK OPTION
K: WITH BOARDLOCK
M: WITHOUT BOARDLOCK

INSULATOR, / DIM E
1: LCP(NATURAL), /3.20±0.25
2: LCP (BLACK), /3.20±0.25
5: LCP(NATURAL), /2.80
6: LCP (BLACK), /2.80

TOLERANCE	APPROVALS	DATE
X.X ±0.30	DRAWN Aqua Chou	09/13/2016
X.XX ±0.20	CHECKED Roger Tsai	09/13/2016
X.XXX ±0.10	APPROVED Roger Tsai	09/13/2016
ANGULAR ±1°		
UNLESS OTHERWISE SPECIFIED	DWG TYPE CUST DWG	PROJECT CODE PHD

TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)



Amphenol®
Amphenol Corporation
Amphenol Taiwan Corporation

PART No. G88MPXX1XXXEU

DWG No. G88MPXX1XXXEU

REV. B

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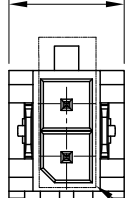


ORIGINAL



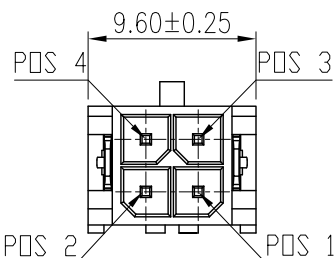
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016	Roger Tsai

6.60±0.25

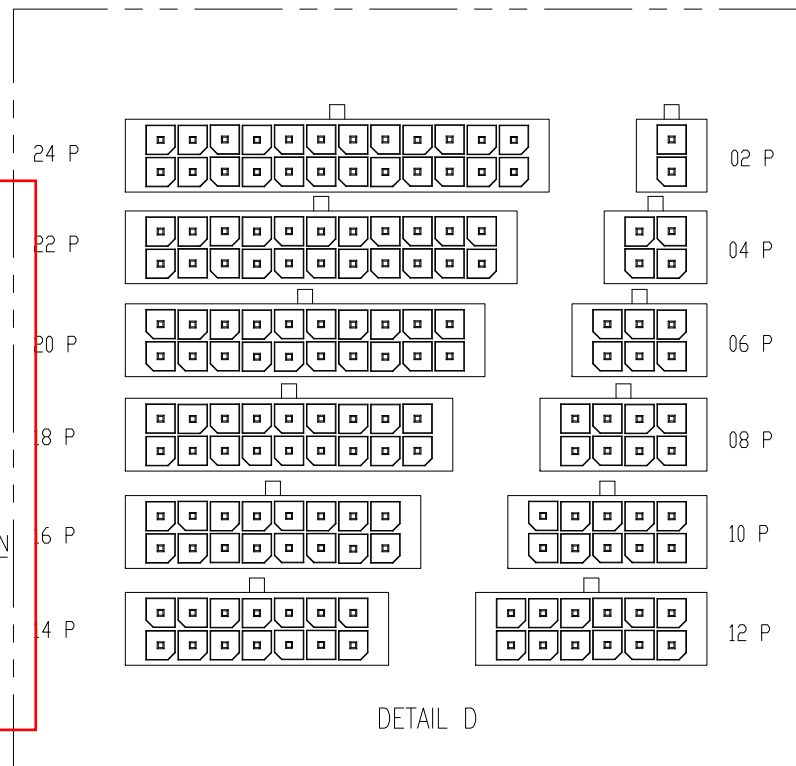
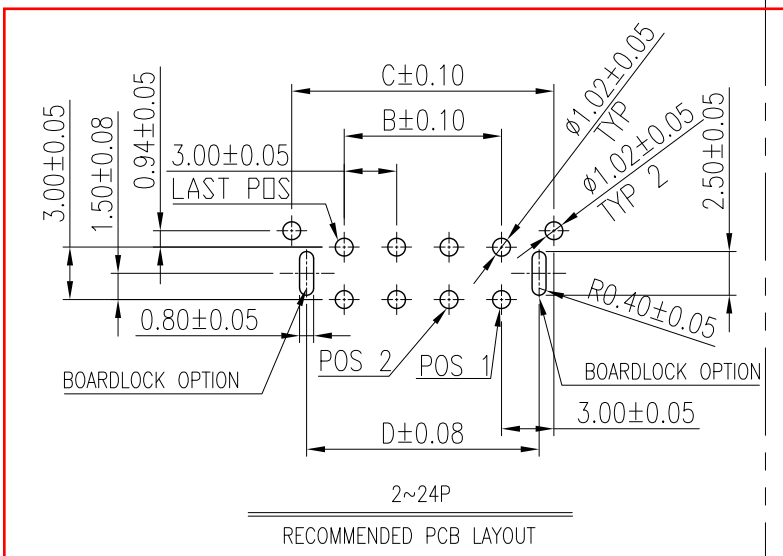
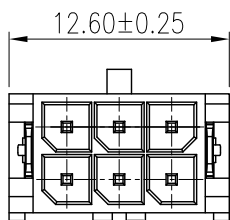


DETAIL D

(2X1POS)



(2X2POS)



TOLERANCE	APPROVALS	DATE	TITLE		Amphenol®		
X. ±0.30	DRAWN Aqua Chou	09/13/2016	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation		
X.X ±0.20	CHECKED Roger Tsai	09/13/2016					
X.XX ±0.10	APPROVED Roger Tsai	09/13/2016			UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU
X.XXX ±0.10	DWG TYPE CUST DWG	PROJECT CODE PHD			SCALE NA	SHEET 2 OF 4	DWG No. G88MPXX1XXXEU
ANGULAR ±1°			UNLESS OTHERWISE SPECIFIED				

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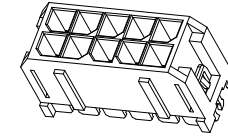


ORIGINAL

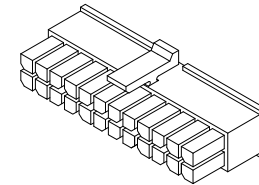


REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016	Roger Tsai

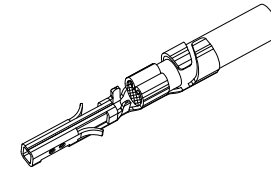
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021XXXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041XXXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061XXXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081XXXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101XXXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121XXXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141XXXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161XXXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181XXXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201XXXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221XXXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241XXXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
 TO ENSURE CURRENT RATING CAPABILITY,
 AMPHENOL HIGH CURRENT PART NUMBERS IN THE
 CHART ARE RECOMMENDED.
 (G88MPH CABLE HOUSING SERIES WITH G88MPC
 CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]		
X.		DRAWN	Aqua Chou	09/13/2016	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation		
X.X	±0.30	CHECKED	Roger Tsai	09/13/2016					
X.XX	±0.20	APPROVED	Roger Tsai	09/13/2016					
X.XXX	±0.10								
ANGULAR	±1°								
UNLESS OTHERWISE SPECIFIED		DWG TYPE	CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3
						SCALE	NA	SHEET	3 OF 4
								PART No.	G88MPXX1XXXEU
								DWG No.	G88MPXX1XXXEU
								REV.	B

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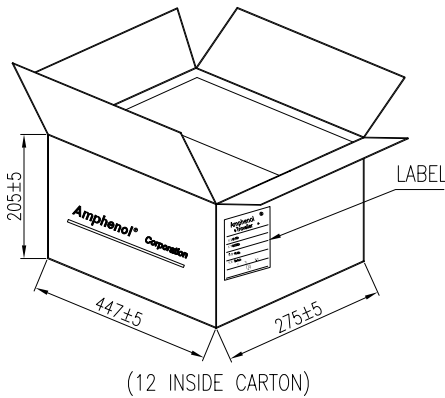
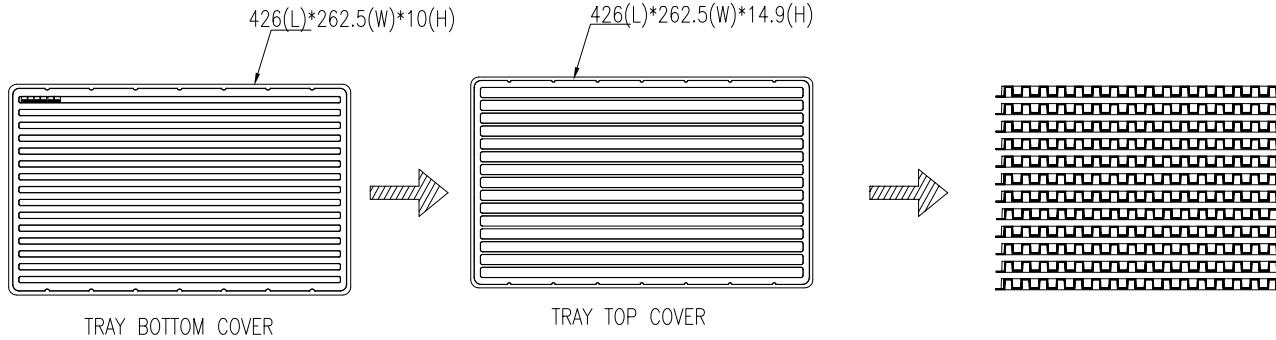
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ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016	Roger Tsai



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
- MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 - ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 - THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol [®]	
X. ±0.30	DRAWN Aqua Chou	09/13/2016	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Roger Tsai	09/13/2016				
X.XXX ±0.10	APPROVED Roger Tsai	09/13/2016				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 4 OF 4	DWG No. G88MPXX1XXXEU REV. B	

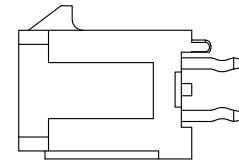
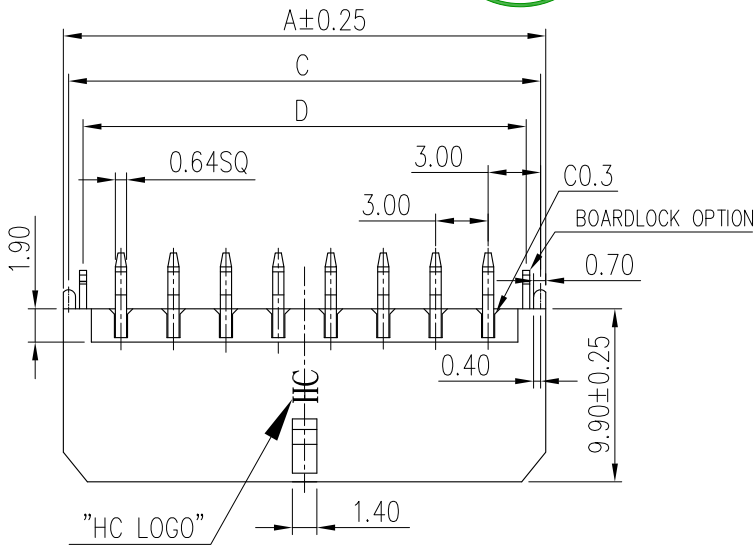
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FOR REFERENCE ONLY

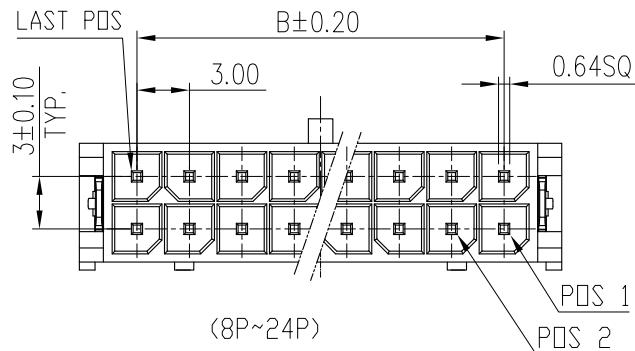
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
PCN_G88MPXX1XXXEU		DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-07-11	Karen Su



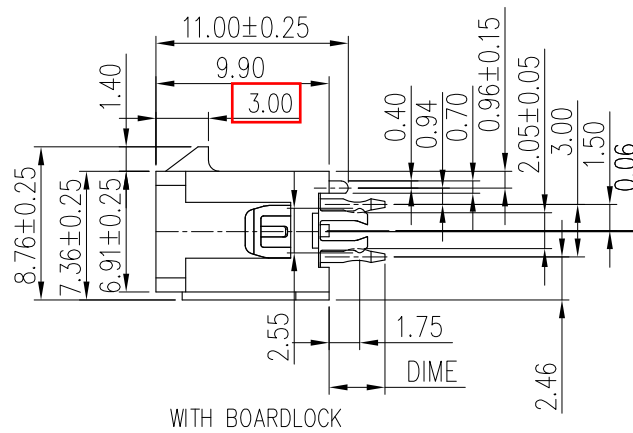
WITHOUT BOARDLOCK

NOTE:

- MATERIAL
INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.
BOARDLOCK: COPPER ALLOY.
- FINISH:
CONTACT: SELECTIVE PLATING. ;
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
BOARDLOCK:
MATTE TIN 100u" MIN. PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- APPLICABLE P.C.BOARD THICKNESS: 1.60mm
- PRODUCT SPECIFICATION REFER TO : PS-7528
- PACKING MUST BE PER AMPHENOL PACKING SPECIFICATION
- TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



(8P~24P)



WITH BOARDLOCK

POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

PART NO. G88MPXX1XXXEU
No. OF CIRCUIT

CONTACT & SOLDERING FINISH
0: GOLD FLASH (OVERALL)
1: 100u" MATTE TIN PLATING (OVERALL)
2: 15u" GOLD PLATING/100u" MATTE TIN
3: 30u" GOLD PLATING/100u" MATTE TIN

BOARDLOCK OPTION
K: WITH BOARDLOCK
M: WITHOUT BOARDLOCK

INSULATOR, / DIM E
1: LCP (NATURAL), /3.20±0.25
2: LCP (BLACK), /3.20±0.25
5: LCP (NATURAL), /2.80^{+0.25}/_{-0.00}
6: LCP (BLACK), /2.80^{+0.25}/_{-0.00}

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30 X.X ±0.20 X.XX ±0.20 X.XXX ±0.10	DRAWN Karen Su CHECKED Joseph Jiang	2022-07-11 2022-07-11	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)	mm	A3	G88MPXX1XXXEU
ANGULAR ±1°	APPROVED Roger Tsai	2022-07-11				
UNLESS OTHERWISE SPECIFIED	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SCALE NA	SHEET 1 OF 4	DWG No. G88MPXX1XXXEU

Amphenol®
Amphenol Corporation
Amphenol Taiwan Corporation

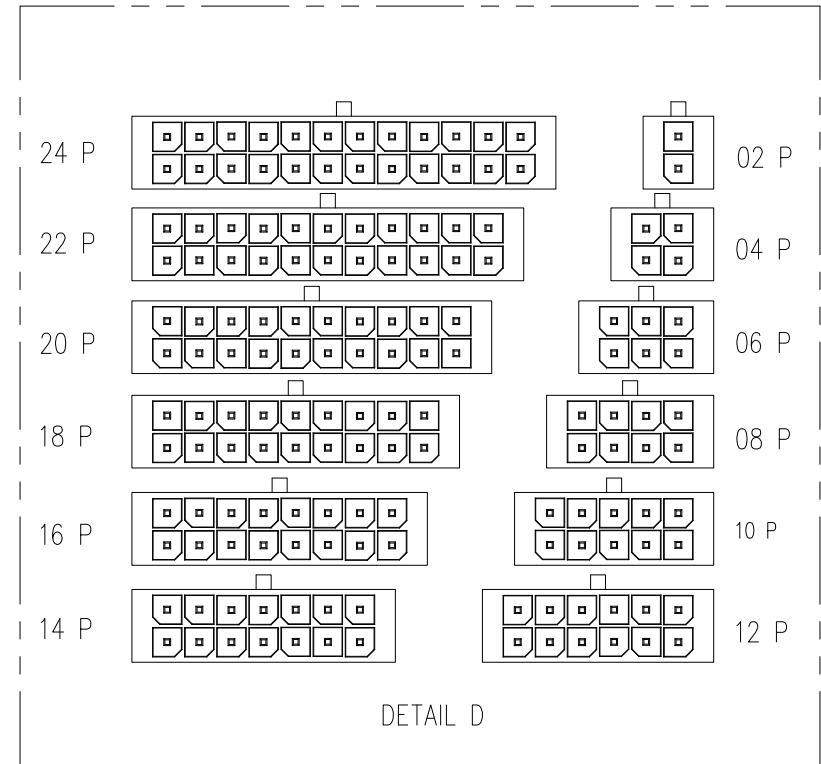
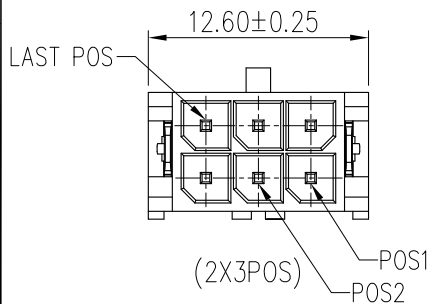
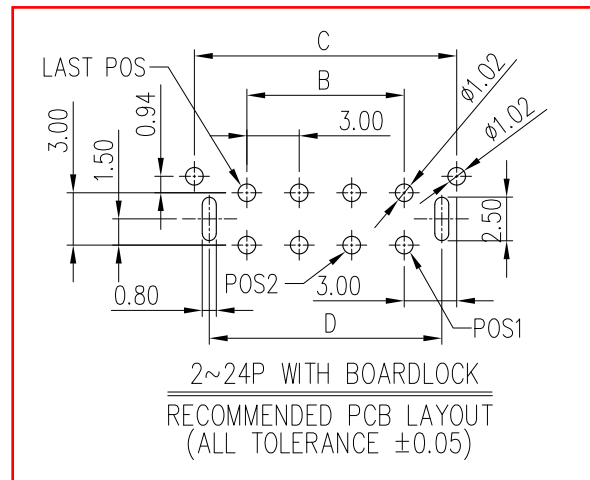
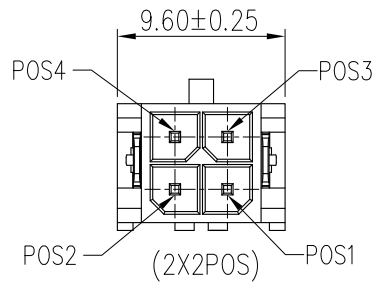
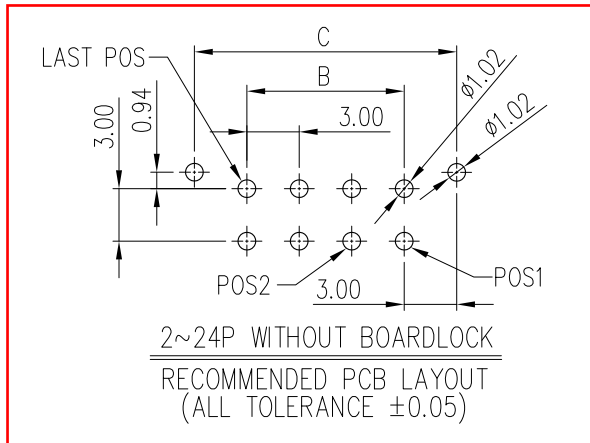
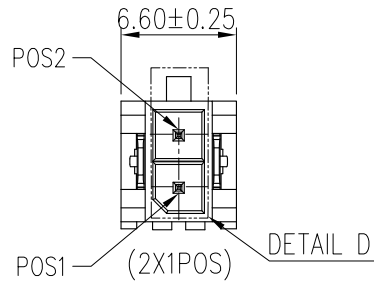
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FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
PCN_G88MPXX1XXXEU		DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-07-11	Karen Su



TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]						
X.		DRAWN	Karen Su	2022-07-11	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation						
X.X	±0.30	CHECKED	Joseph Jiang	2022-07-11									
X.XX	±0.20	APPROVED	Roger Tsai	2022-07-11									
X.XXX	±0.10	DWG TYPE	CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3	PART No.	G88MPXX1XXXEU		
ANGULAR	±1°					SCALE	NA	SHEET	2 OF 4	DWG No.	G88MPXX1XXXEU	REV.	
UNLESS OTHERWISE SPECIFIED													

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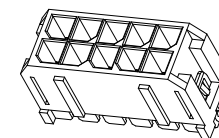
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



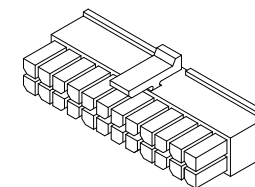
FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
PCN_G88MPXX1XXXEU		DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-07-11	Karen Su

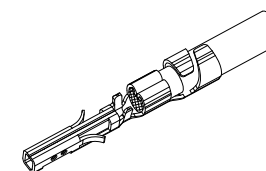
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021XXXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041XXXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061XXXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081XXXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101XXXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121XXXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141XXXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161XXXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181XXXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201XXXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221XXXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241XXXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



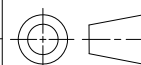
AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
TO ENSURE CURRENT RATING CAPABILITY,
AMPHENOL HIGH CURRENT PART NUMBERS IN THE
CHART ARE RECOMMENDED.
(G88MPH CABLE HOUSING SERIES WITH G88MPC
CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]						
X.		DRAWN	Karen Su	2022-07-11	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation						
X.X	±0.30	CHECKED	Joseph Jiang	2022-07-11									
X.XX	±0.20	APPROVED	Roger Tsai	2022-07-11									
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3	PART No.	G88MPXX1XXXEU	
							SCALE	NA	SHEET	3 OF 4	DWG No.	G88MPXX1XXXEU	REV.

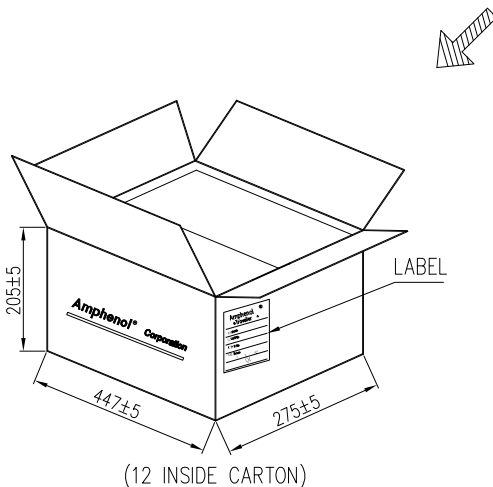
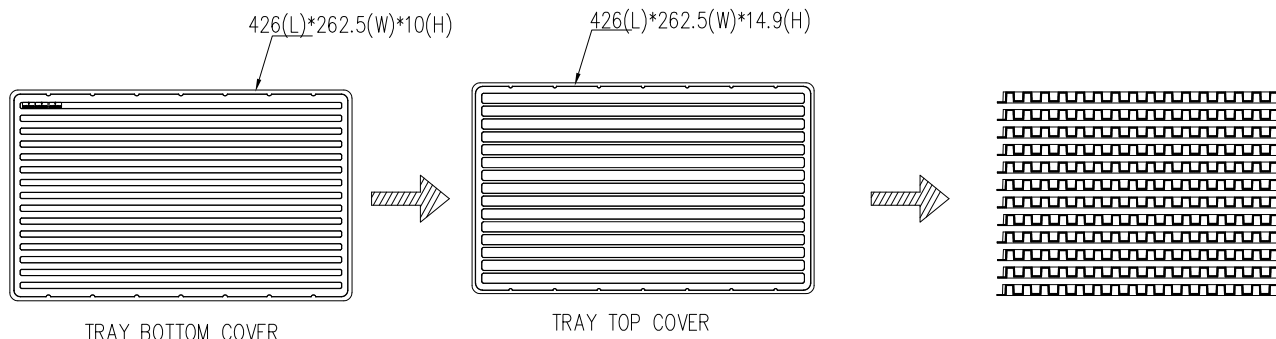


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FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
PCN_G88MPXX1XXXEU		DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-07-11	Karen Su



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:
 1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol [®]	
X. ±0.30	DRAWN Karen Su	2022-07-11	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Joseph Jiang	2022-07-11				
X.XXX ±0.10	APPROVED Roger Tsai	2022-07-11				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 4 OF 4	DWG No. G88MPXX1XXXEU REV.	